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Date of Deposit: June 2, 2005

Case No. 9905/26
Client No. BIF023238/US

UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
FOURNEL et al.)
Serial No.: Not Yet Assigned) Examiner:
Filing Date: Herewith) Not Yet Assigned
For: METHOD OF PRODUCING) Group Art Unit:
A COMPLEX STRUCTURE BY) Not Yet Assigned
ASSEMBLING STRESSED)
STRUCTURES)

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Dear Sir:

In accordance with the duty of disclosure under 37 C.F.R. §1.56 and §§1.97-1.98, and more particularly in accordance with 37 C.F.R. §1.97(b), Applicants hereby cite the following references:

No.	Date of Publication	Patentee/Applicant/Assignee
5,131,968	07/21/1992	
4,832,253	05/23/1989	
FR 2 789 518 A1	08/11/2000	
EP 0 895 282 A3	01/26/2000	
EP 0 895 282 A2	02/03/1999	
EP 0 410 679 A1	01/30/1991	
EP 0 383 391 A1	08/22/1990	
1-169917	07/05/1999	
Feijoo et al., "Prestressing of Bonded Wafers", Proceedings of the 1st International Symposium on Semiconductor Wafer Bonding, Science Technology and Applications, Vol. 92-7, The Electrochemical Society (1992), pp. 230-238.		
Feijoo et al., "Generalized Formula for Curvature Radius and Layer Stresses Caused by Thermal Strain in Semiconductor Multilayer Structures," Appl. Phys. 54(1), 1983, page 83.		
S. Timoshenko, "Analysis of Bi-Metal Thermostats," J. Opt. Soc. Am. 11 (1925), page 233-256.		

For the Examiner's convenience, Applicants are enclosing Form PTO-1449 (one sheet), and as each of the listed references is in English, no further commentary is believed to be necessary, 37 C.F.R. §1.98(a)(3). Applicant respectfully requests the Examiner's consideration of the above references and entry thereof into the record of this application.

Also enclosed is a copy of the International Search Report issued on May 3, 2004 for corresponding PCT Application No. PCT/FR03/03590 of the above-identified application.

By submitting this Statement, Applicants are attempting to fully comply with the duty of candor and good faith mandated by 37 C.F.R. §1.56. As such, this Statement is not intended to constitute an admission that any of the enclosed references, or other information referred to therein, constitutes "prior art" or is otherwise "material to patentability," as that phrase is defined in 37 C.F.R. §1.56(a).

Applicants have calculated no fee to be due in connection with the filing of this Statement. However, the Director is authorized to charge any fee deficiency associated with the filing of this Statement to a deposit account, as authorized in the Transmittal accompanying this Statement.

Respectfully submitted,

June 2, 2005



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10/537679
 JC09 Rec' CT/PTO 32 JUN 2005

FORM PTO-1449	SERIAL NO. Not Yet Assigned	CASE NO. 9905/26 (BIF023238/US)
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE Herewith	GROUP ART UNIT Not Yet Assigned
APPLICANTS: FOURNEL et al.		

REFERENCE DESIGNATION

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER Number-Kind Code (if known)	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
A1	5,131,968	07/21/1992	Wells et al.		
A2	4,832,253	05/23/1989	Kloucek et al.		

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER Number-Kind Code (if known)	DATE	COUNTRY	CLASS/ SUBCLASS	TRANSLATION YES OR NO
A3	FR 2 789 518 A1	08/11/2000	France		
A4	EP 0 895 282 A3	01/26/2000	EPO		
A5	EP 0 895 282 A2	02/03/1999	EPO		
A6	EP 0 410 679 A1	07/24/1999	EPO		
A7	EP 0 383 391 A1	02/12/1990	EPO		
A8	1-169917	07/05/1999	Japan		Abstract

EXAMINER INITIAL	OTHER ART - NON PATENT LITERATURE DOCUMENTS (Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.)	
A9	Feijoo et al., "Prestressing of Bonded Wafers", Proceedings of the 1st International Symposium on Semiconductor Wafer Bonding, Science Technology and Applications, Vol. 92-7, The Electrochemical Society (1992), pp. 230-238.	
A10	Feijoo et al., "Generalized Formula for Curvature Radius and Layer Stresses Caused by Thermal Strain in Semiconductor Multilayer Structures," Appl. Phys. 54(1), 1983, page 83.	
A11	S. Timoshenko, "Analysis of Bi-Metal Thermostats," J. Opt. Soc. Am. 11 (1925), page 233-256.	

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.